

EMB-BSW1

Thermal Image Analysis Report

Summary	<input type="checkbox"/> Pass <input type="checkbox"/> Fail <input checked="" type="checkbox"/> Pass with Deviation Comment: <u>There are six temperature point marginal passed, hope to get improvement for the next generation.</u>			
	Test Result Summary			
	Critical	Major	Minor	Enhancement
Defect Found	0	0	0	6
Defect Unsolved	0	0	0	6

Issue date

2016 / 04 / 07

QE Manager

KJ Wang

Test Engineer

Jerry Chen

Sample Configuration & Quantity Under Test

- **Model name : EMB-BSW1 R1.02**
- **CPU Board : Intel Pentium N3710 1.6 GHz**
- **CPU : Intel Pentium N3710 1.6 GHz**
- **Chipset : Intel Braswell**
- **BIOS : R1.3 (EBW1AM13) (03/07/2016)**
- **Memory : Transcend DDR3L 1600 SO 4GB (SEC / K4B4G0846B) *2**
- **2.5" SATA SSD: OCZ / TRN100-25SAT3-240G 240GB**
- **Test Software : Windows 8 / Run PassMark Burn In Test 8.1 Pro**
- **AT Power Supply: Zippy HG2-6400P / 400W**
- **Heat sink :**

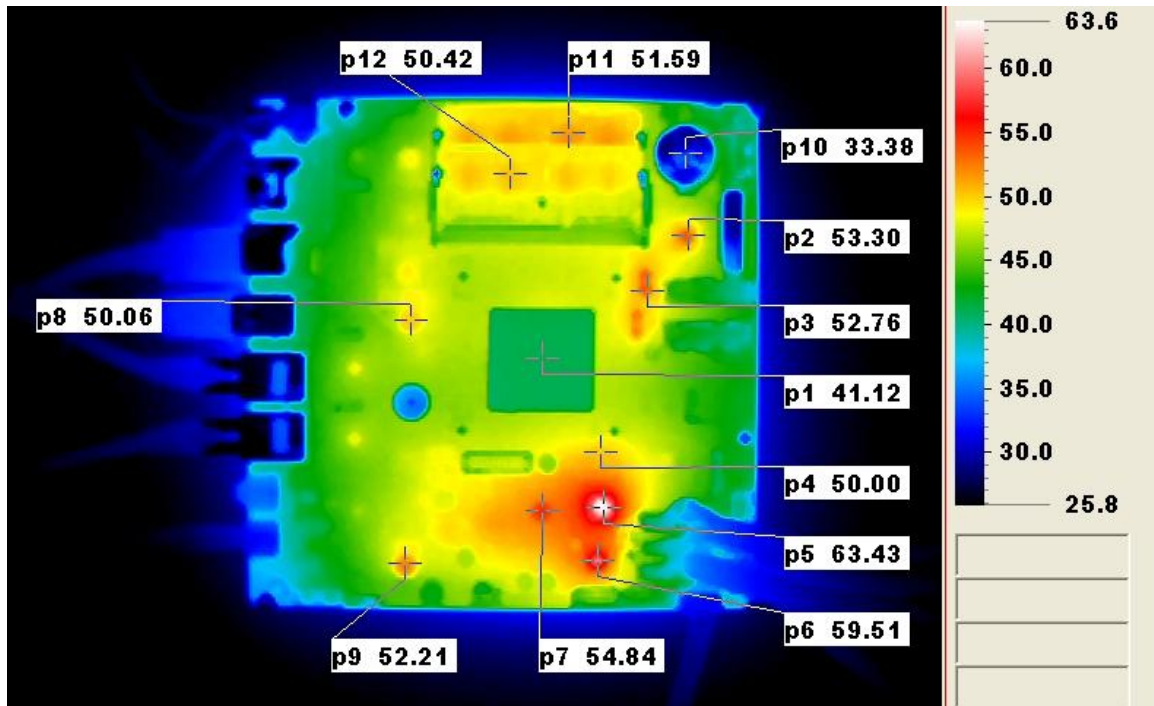


Thermal Image Analysis

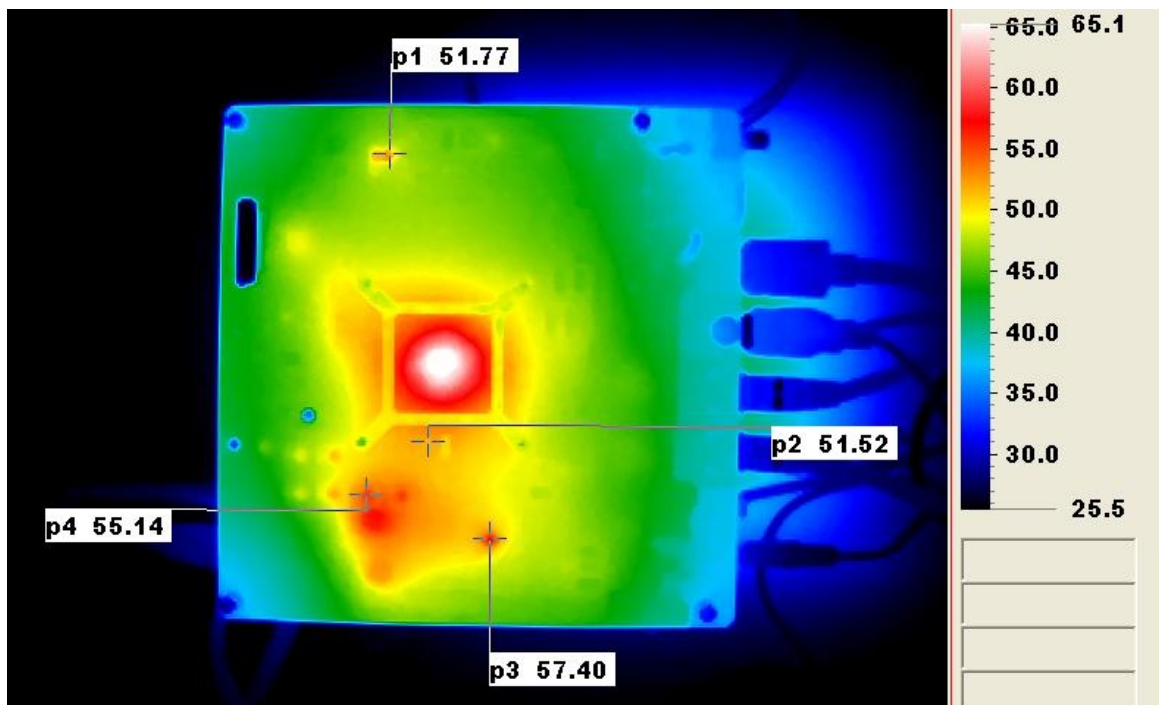
1. Test Date: 04-06-2016
2. Test Product: EMB-BSW1
3. Test Site: AAEON QE Dept.
4. Temperature Measurement:
 - 4.1. 20 Channel Thermal Recorder:
 - 4.1.1 OMRON Inc,
 - 4.2.2 Model: ZR-RX45
Date of Calibration: 12/18/2015
Serial Number: H30481978
 - 4.2. IR Scanner: Infrared Camera
 - 4.2.1 NEC Avio Infrared Technologies Co., Ltd.
 - 4.2.2 Model: Thermo GEAR G100W2-D
Date of Calibration: 12/01/2015
Serial Number: 1051444
5. Test Condition:
 - Test by DA-100: 25.0°C with Heat sink
6. Take Picture Time:
 - After power on 2 hours

Temperature Profile Test:

Front Side:

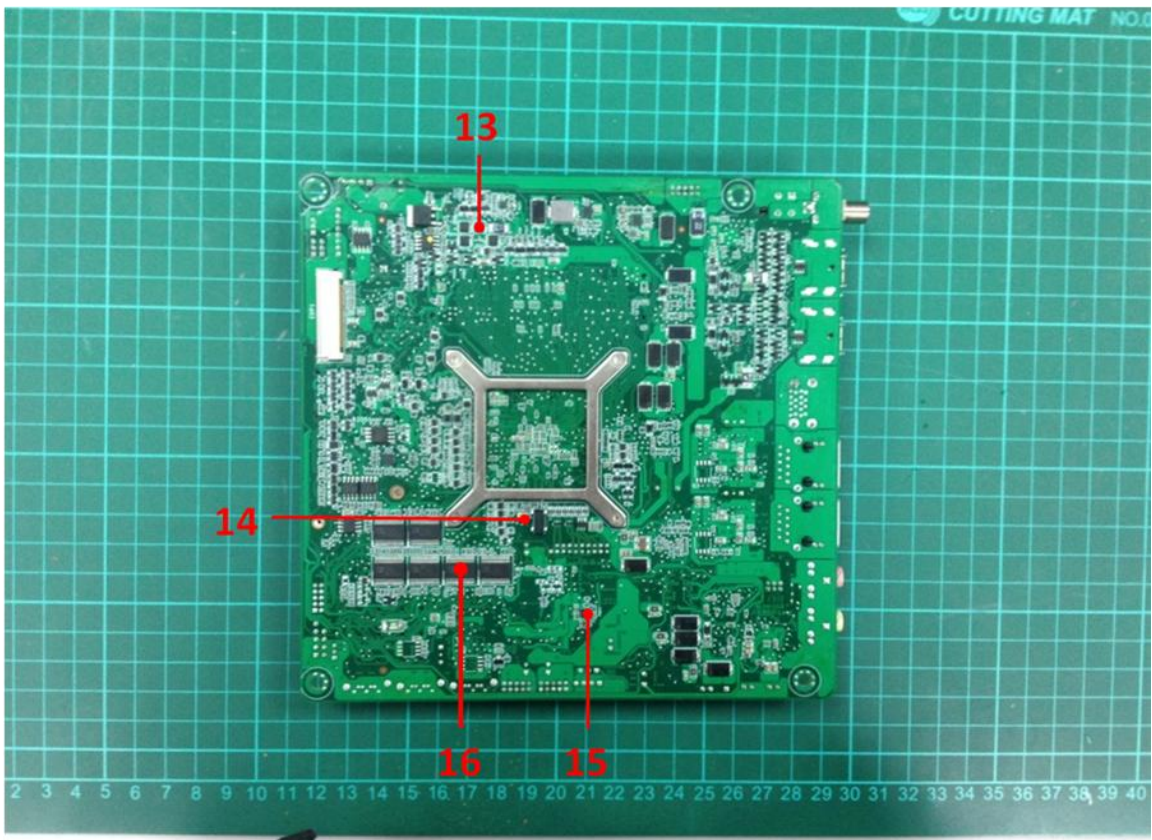
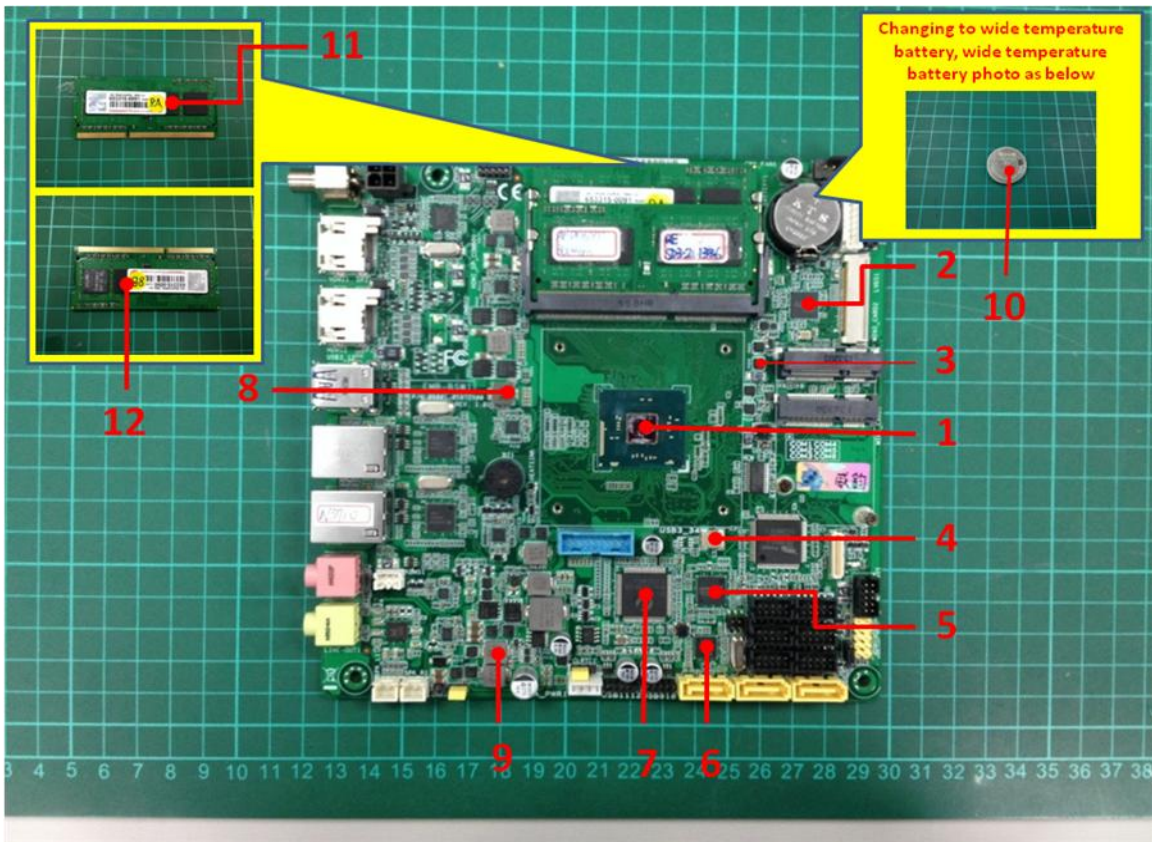


Back Side



Terminal Recorder:

Measuring Thermal Couple Position :



Using OMRON Inc / ZR-RX45 test

Point	Position	Describe	Tc (*1) (°C)	TAT(*2) TPT(*3)		Note
				25.0°C	50°C	
1	CPU	Intel Pentium N3710 1.6 GHz	90	65.9	90.9	Note 6
2	LVU1	C.S CH7511B-BF QFN68	125	59.5	84.5	
3	PQ26	N-MOSFET EMB20N03V POWER PAK	150	63.3	88.3	
4	U11	OSC 48MHZ SMD 3.3V 15PF/50PPM	85	60.3	85.3	Note 6
5	Y1U1	C.S ASM1184E QFN-64L	95	71.6	96.6	Note 6
6	U26	C.S ASM1061 (A3) QFN48L	95	67.1	92.1	Note 6
7	U27	BRIDGE PI7C9X440SLBFDE PCIE TO USB LQFP-128	100	63.2	88.2	
8	PL7	INDUCTOR 0.36UH/24A 20%	140	57.8	82.8	
9	PL2	INDUCTOR 4.7UH/5.5A SMD 20%	140	60.1	85.1	
10	BATTERY	BATT-LI MAXELL//CR2032 3V/210mAh <G> (Wide Temperature)	85	46.1	71.1	
11	RAM-1	Memory chipset (SEC / K4B4G0846B)	95	55.2	80.2	
12	RAM-2	Memory chipset (SEC / K4B4G0846B)	95	54.8	79.8	
13	PQ36	N-MOSFET EMB20N03V POWER PAK	150	60.5	85.5	
14	SX1	XTAL 19.2MHZ 7PF/10PPM	100	61.2	86.2	
15	PU21	LDO REG. UP0132PDDA	100	67.9	92.9	Note 6
16	U19	INTERFACE ADM213EARSZ SSOP-28	100	65.6	90.6	Note 6
17	N/A	Air Temperature	N/A	25	50	

Note(*):

- "Tc" indicates the component's case maximum temperature value specified in its datasheet.
- "TAT" indicates the actual measured temperature under 25°C working environmental.
- "TPT" indicates the predicted temperature under product specification.
- Judgment Criteria:**
 - **Fail** : Tm > Tc+5°C; The measured value is over specification plus margin.
 - **Margin** : Tc+5°C > Tm > Tc-10°C; The measured value is within specification with margin.
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
 - **Pass** : Tm < Tc-10°C; The measured value is with safety margin.
- RTC battery avoid to put on heat position. Please do not exceed battery temperature specification.
- Defect NO. : [W150103QED01](#)